As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled BOND PAD REROUTING ELEMENT, REROUTED SEMICONDUCTOR DEVICES INCLUDING THE REROUTING ELEMENT, STACKED CHIP ASSEMBLIES INCLUDING THE REROUTED SEMICONDUCTOR DEVICES, AND METHODS, the specification of which (check one):

is attached hereto.				
was filed on	as United States application serial no.		 Ne 10 on	
□ was filed on	as PCT international application no.	and was amended under FC1 Aluc	ic 19 0ii	
I hereby state that I have re- referred to above.	viewed and understand the contents of the abo	ve-identified specification, including the c	laims, as amended by any	amendment
I acknowledge the duty to d matter claimed in this application	isclose to the U.S. Patent and Trademark Offion, as "materiality" is defined in Title 37, Co	ce all information known to me to be mate de of Federal Regulations § 1.56.	erial to the patentability o	f the subject
certificate or § 365(a) of any Peattached continuation page and	rity benefits under Title 35, United States Cod CT international application(s) designating at have also identified below and on any attacher) designating at least one country other than the	east one country other than the United State of continuation page any foreign application	ates of America listed belon for patent or inventor's	ow and on any certificate or an
Prior foreign/PCT application(s	s):		Priority C	laimed
(number)	(cour	try) (day/month/	'year filed) Yes	No
(number)	(cour	try) (day/month/	year filed) Yes	No
designating the United States of application is not disclosed in an duty to disclose to the U.S. Pate	nder Title 35, United States Code, § 120 of an America listed below and on any attached cony such prior application in the manner provident and Trademark Office all information known available between the filing date of such prior to the such pri	ntinuation page and, insofar as the subject led by the first paragraph of Title 35, Unit wn to me to be material to patentability as	t matter of each of the cla ted States Code, § 112, I defined in Title 37, Code	ims of this acknowledge the e of Federal
(application serial no	(filing date)	(status - pendi	ng, patented or abandoned	1)
(application serial no	o.) (filing date)	(status - pendir	ng, patented or abandoned	1)
I hereby claim the benefit ur	nder Title 35, United States Code, § 119(e) of	any United States provisional application	(s) listed below:	
(provisional applicati	on no.) (filing date)			
therewith:	g Registered Practitioners to prosecute this ap			Office connected
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: David J. Corisis Inventor's signature

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DECLARATION FOR PATENT APPLICATION (continuation page)

Investion title: BOND PAD REROUTING ELEMENT, REROUTED SEMICONDUCTOR DEVICES INCLUDING THE REROUTING ELEMENT, STACKED CHIP ASSEMBLIES INCLUDING THE REROUTED SEMICONDUCTOR DEVICES, AND METHODS

Inventor name(s) appearing on first declaration page: David J. Corisis

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